

Cookson Group Plaskon® 3100LS Mineral Filled Conventional Encapsulant (discontinued **)

Category : Polymer , Thermoset , Epoxy , Epoxy, Encapsulating, Glass or Mineral Filled , Filled/Reinforced Thermoset

Material Notes:

Test specimens were transfer molded and post cured 4 hours at 175°C. A semiconductor grade encapsulant suitable for a wide range of applications ranging from small SOICs to moderate lead count DIPs.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Cookson-Group-Plaskon-3100LS-Mineral-Filled-Conventional-Encapsulant-nbspdiscontinued-.php

Physical Properties	Metric	English	Comments
Density	1.85 g/cc	0.0668 lb/in ³	
Spiral Flow	64.0 - 88.0 cm	25.2 - 34.6 in	177°C/1000 psi

Mechanical Properties	Metric	English	Comments
Hardness, Shore D	73	73	
Tensile Strength, Ultimate	107 MPa	15500 psi	
Flexural Strength	139 MPa	20200 psi	

Thermal Properties	Metric	English	Comments
CTE, linear	21.0 µm/m-°C	11.7 µin/in-°F	
	@Temperature 20.0 °C	@Temperature 68.0 °F	
CTE, linear, Transverse to Flow	69.0 µm/m-°C	38.3 µin/in-°F	
	@Temperature 20.0 °C	@Temperature 68.0 °F	
Thermal Conductivity	0.700 W/m-K	4.86 BTU-in/hr-ft ² -°F	
Glass Transition Temp, Tg	155 °C	311 °F	
Flammability, UL94	V-0	V-0	
	@Thickness 3.20 mm	@Thickness 0.126 in	
	V-0	V-0	
	@Thickness 3.20 mm	@Thickness 0.126 in	

Electrical Properties	Metric	English	Comments
Dielectric Constant	4.0	4.0	
	@Frequency 1000 Hz	@Frequency 1000 Hz	

Dielectric Strength Electrical Properties	17.0 kV/mm Metric	432 kV/in English	Comments
Dissipation Factor	0.0040	0.0040	
	@Frequency 1000 Hz	@Frequency 1000 Hz	
Arc Resistance	180 sec	180 sec	

Processing Properties	Metric	English	Comments
Processing Temperature	171 - 193 °C	340 - 379 °F	Molding temperature

Contact Songhan Plastic Technology Co.,Ltd.

Website : www.lookpolymers.com

Email : sales@lookpolymers.com

Tel : +86 021-51131842

Mobile : +86 13061808058

Skype : lookpolymers

Address : United North Road 215,Fengxian District, Shanghai City,China